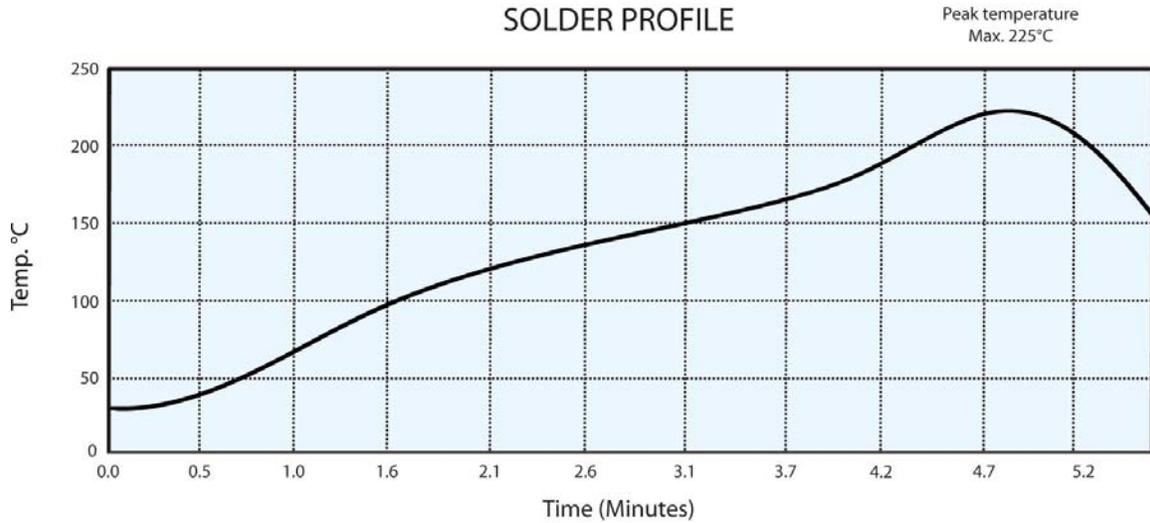
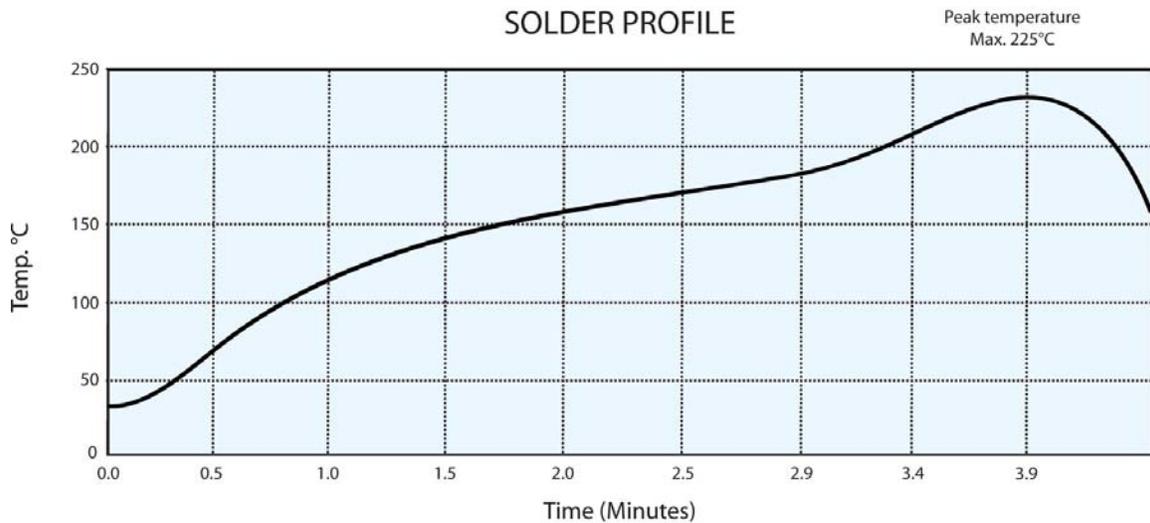


**Recommended Solder Conditions for  
Non RoHS Compliant (Leaded) Surface Mount Ceramic Filters:  
SD, MXD & SMC Series**



**Recommended Solder Conditions for  
Non RoHS Compliant (Leaded) Surface Mount Filters:  
MS Series**



If aqueous cleaning is used for flux removal, bake parts at least 1 minute at 80°C Maximum after water rinse.

-Reflow must be done with alloys SN62 or SN63

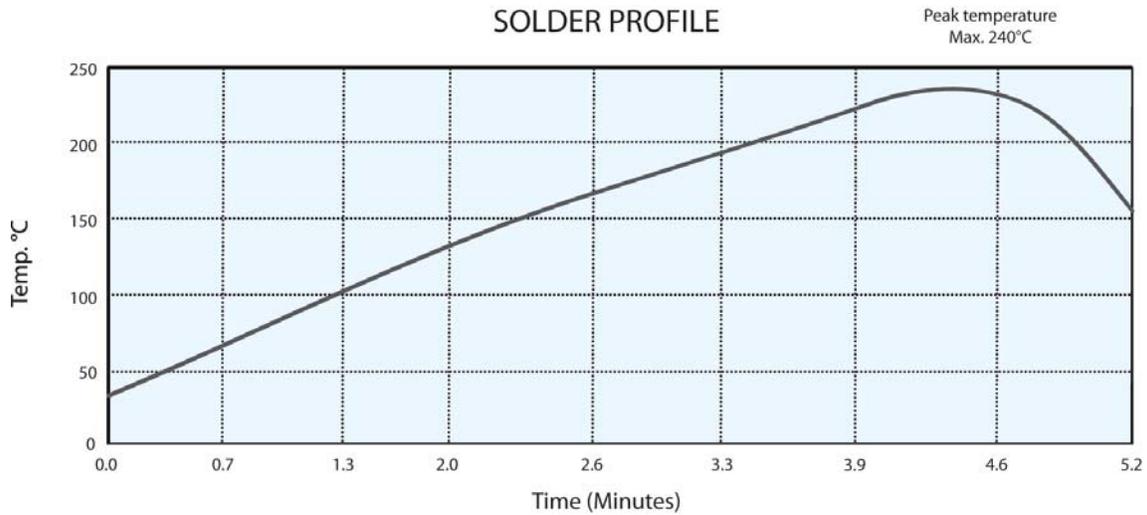
-Registration of solder paste should cover a minimum of 90% of in/out pads, and the thickness should be .006" minimum to .010" maximum.

-Pretinned with an SN90/10 alloy.

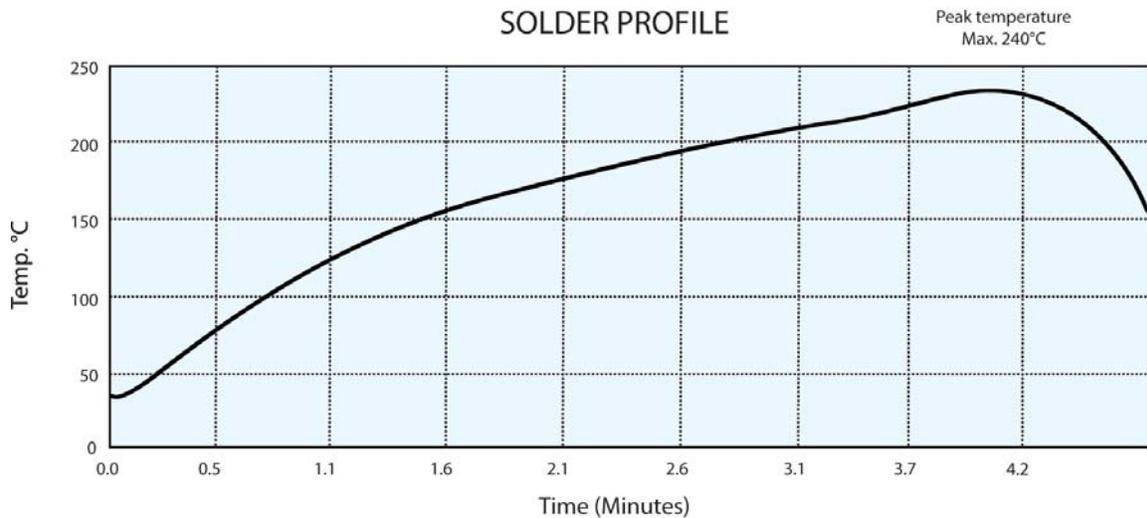
-No solderability problems should occur if prior recommendations are followed.

NOTE: Must apply solder paste in conformance with layout printed circuit design (registration) as shown on Lark Engineering Catalog. MS series page 12, SD series page 18, LMS series page 64, HMS series page 70 and MXD series page 55.

**Recommended Solder Conditions for  
RoHS Compliant (Lead Free) Surface Mount Ceramic Filters:  
SD, MXD & SMC Series**



**Recommended Solder Conditions for  
RoHS Compliant (Lead Free) Surface Mount Filters  
MS Series**



If aqueous cleaning is used for flux removal, bake parts at least 1 minute at 80°C Maximum after water rinse.

- Lark recommends using SAC305 (Tin / Silver / Copper) or Sn96/Ag4 (Tin / Silver) solder paste.
- Alternative alloys may be used, provided the liquidous temperature does not exceed 220°C.
- Registration of solder paste should cover a minimum of 90% of in/out pads, and the thickness should be .006" minimum to .010" maximum.
- No solderability problems should occur if prior recommendations are followed.

NOTE: Must apply solder paste in conformance with layout printed circuit design (registration) as shown on Lark Engineering Catalog. MS series page 12, SD series page 18, LMS series page 64, HMS series page 70 and MXD series page 55.